## Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**
[List multiple models if applicable.]

HP Chromebook 14 G4

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm MB/DB</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries battery</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td></td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](http://example.com).
Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td></td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove base rear rubber foot -L & -R
2. Remove screw rubber foot -L & -R
3. Remove dimple rubber
4. Dis-fasten BASE screw*13
5. Pull out FFC*2 , Cable *(Power, Touchpad, keyboard membrane)
6. Dis-fasten battery screw *8
7. Remove battery
8. Pull out wire cable *4 (LCD, DC, SPEAKER, WLAN)
9. Dis-fasten daughter boards screw *2
10. Remove daughter boards
11. Dis-fasten main boards screw *5
12. Remove mai boards & WLAN card
13. Remove speaker -L & -R
14. Dis-fasten HEAT SINK screw*2
15. Remove HEAT SINK
16. Dis-fasten Hinge screw*2
17. Remove Screw MYLAR -L & -R
18. Dis-fasten LCD Bezel screws*2
19. Remove LCD bezel
20. Dis-fasten Hinge screw*8
21. Remove Hinge
22. Dis-fasten LCD module screw*4
23. Pull out LCD cable & camera cable
24. Remove LCD module
25. Remove camera
26. Remove Antenna cables

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

3.21 Total part disassembly
3.22 Remove base rubber foot -L & -R and screw rubber foot -L & -R and dimple rubber

3.23 Remove TOP assy
3.24 Remove battery & Touchpad & & KB Hook

3.25 Remove daughter boards*2 (DB, WLAN,)

3.26 Remove motherboard & speaker -L & -R & dc in cable & heat sink
3.27 Remove Screw Mylar -L & -R and LCD bezel

3.28 Remove Panel

3.29 Remove Camera module and Hinge -L & -R & LCD cable & Antenna cables